UNR31AVG

Silicon PNP epitaxial planar type

For digital circuits

■ Features

- Suitable for high-density mounting downsizing of the equipment
- Contribute to low power consumption

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-50	V	
Collector-emitter voltage (Base open)	V _{CEO}	-50	V	
Collector current	I_{C}	-80	mA	
Total power dissipation	P _T	100	mW	
Junction temperature	T_j	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

■ Package

- Code SSSMini3-F2
- Marking Symbol: EP
- Pin Name
 - 1: Base
 - 2: Emitter
 - 3: Collector

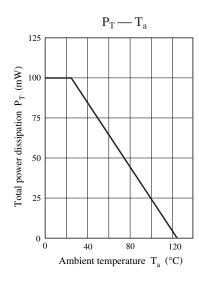
■ Internal Connection

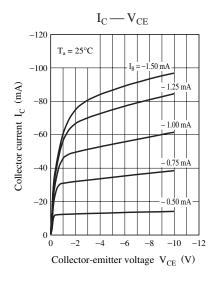
$$R_1 (2.2 \text{ k}\Omega)$$
 $B \circ - \text{W} \circ C$
 $R_2 (2.2 \text{ k}\Omega)$
 $C \circ E$

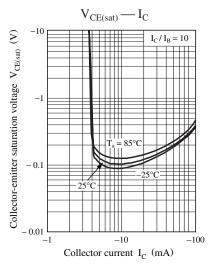
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

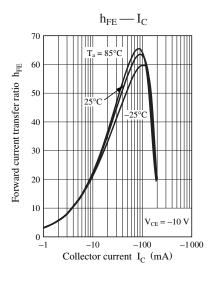
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10 \ \mu A, \ I_E = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -50 \text{ V}, I_{E} = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -50 \text{ V}, I_{B} = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -6 \text{ V}, I_C = 0$			-2.0	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	6		20	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -10 \text{ mA}, I_B = -1.5 \text{ mA}$			- 0.25	V
Output voltage high-level	V _{OH}	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	R ₁		-30%	2.2	+30%	kΩ
Resistance ratio	R ₁ / R ₂		0.7	1.0	1.3	_
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

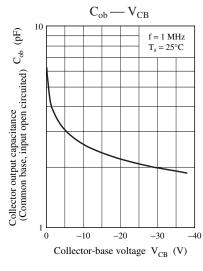
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

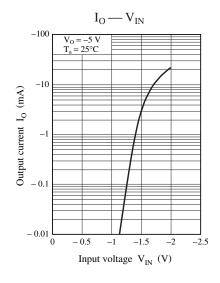


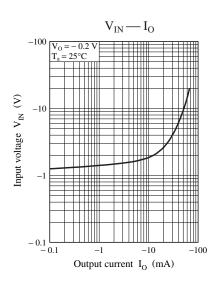






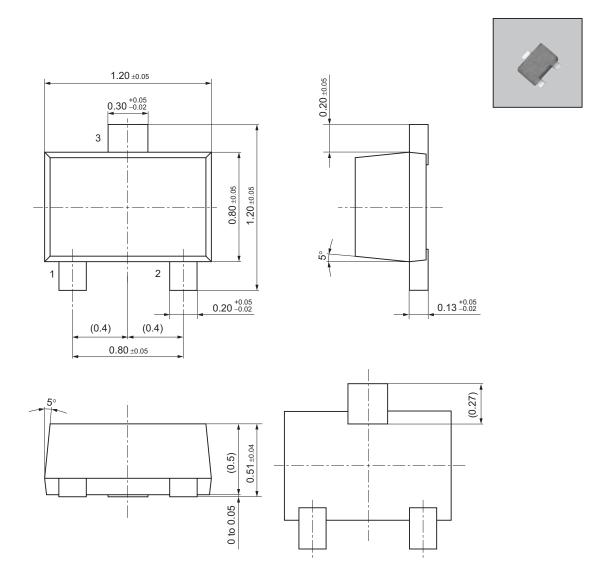






SSSMini3-F2

Unit: mm



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